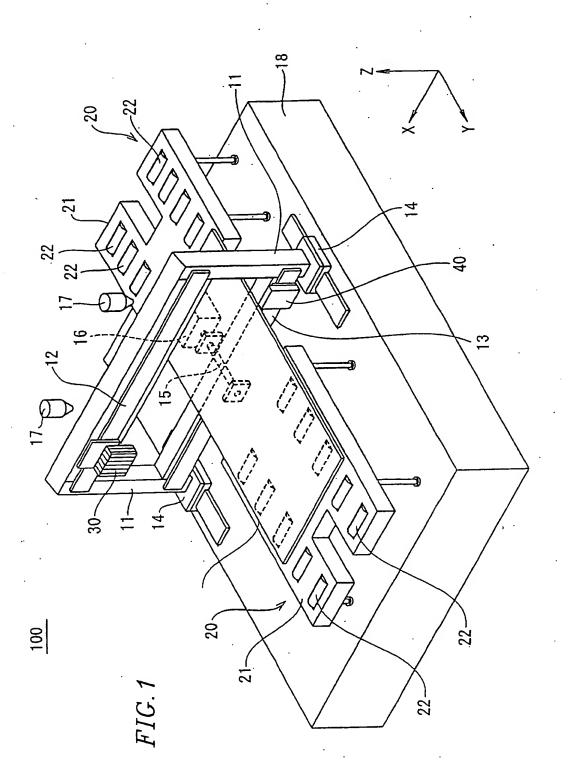
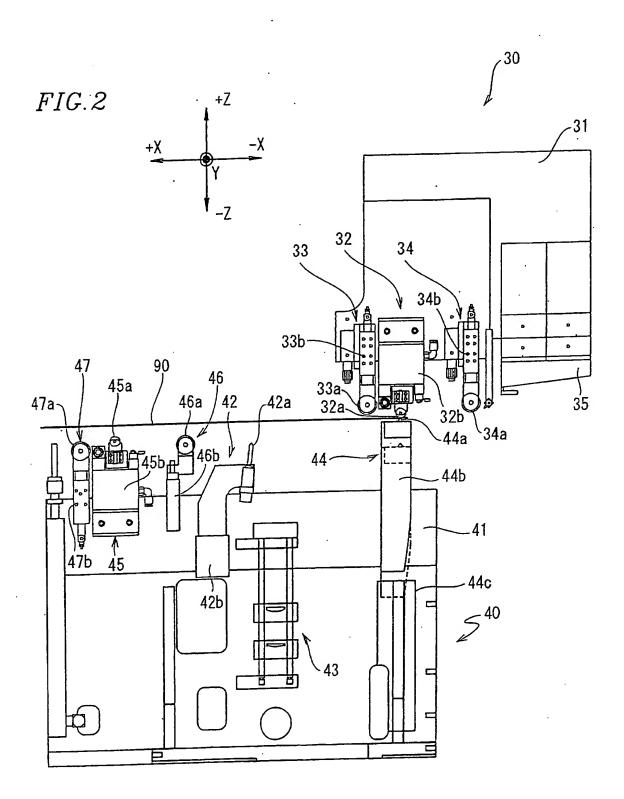
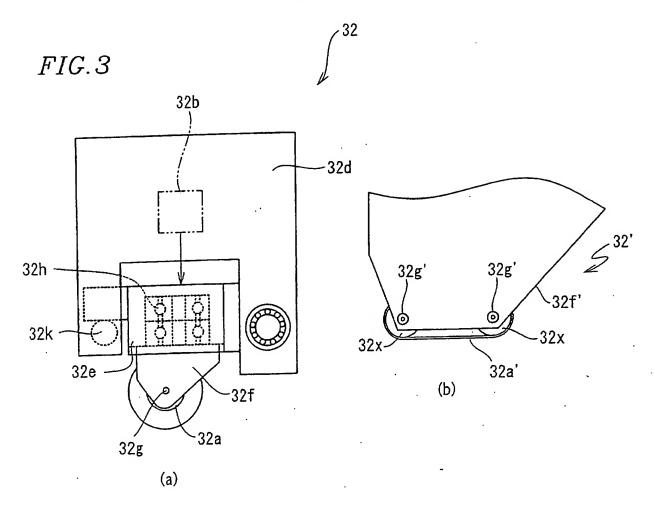
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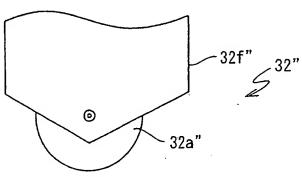


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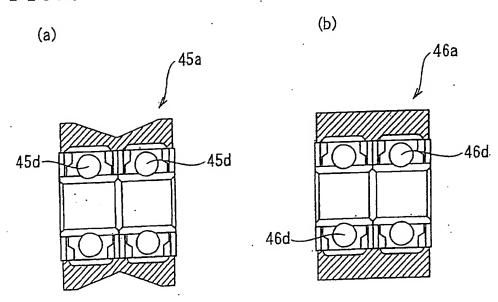




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FIG. 4



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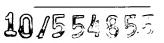
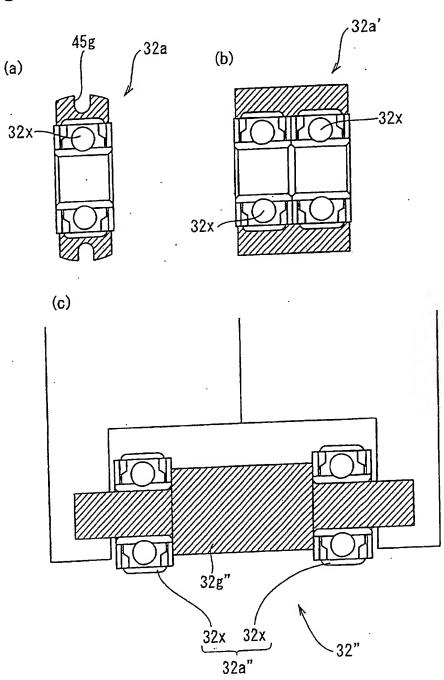
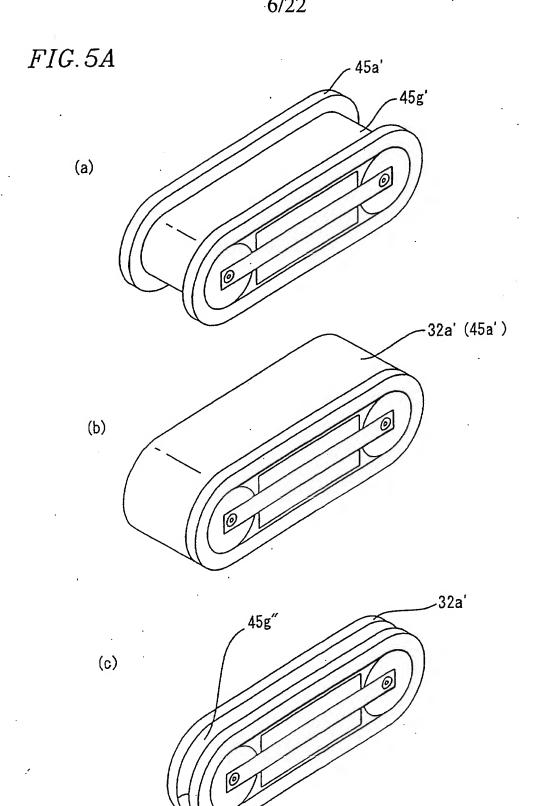


FIG.5

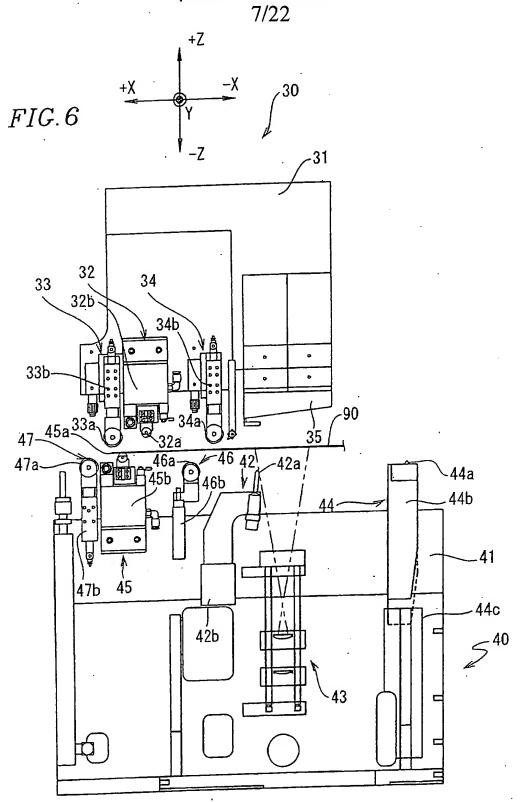


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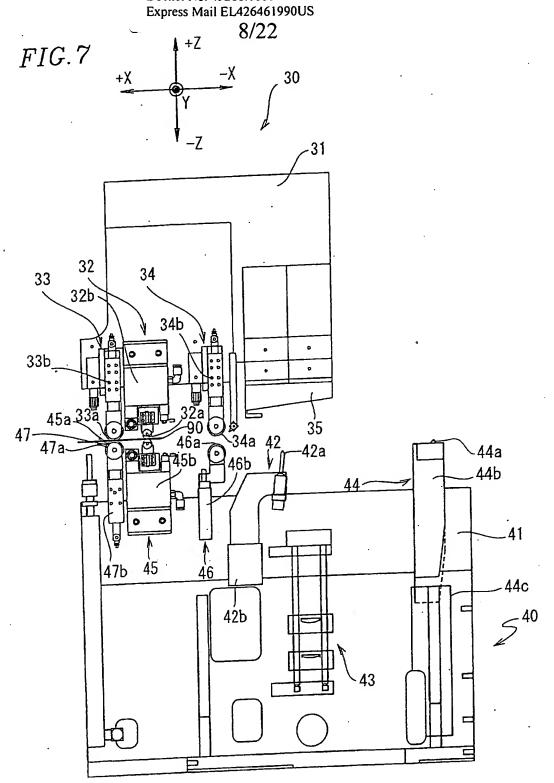


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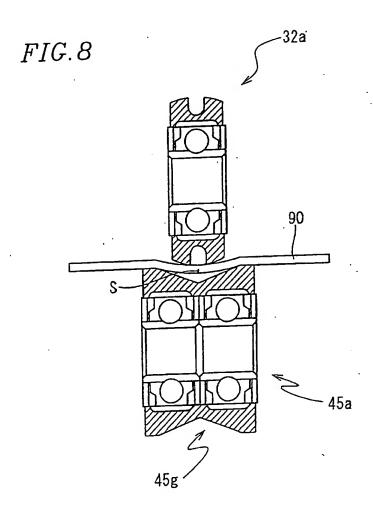


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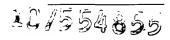


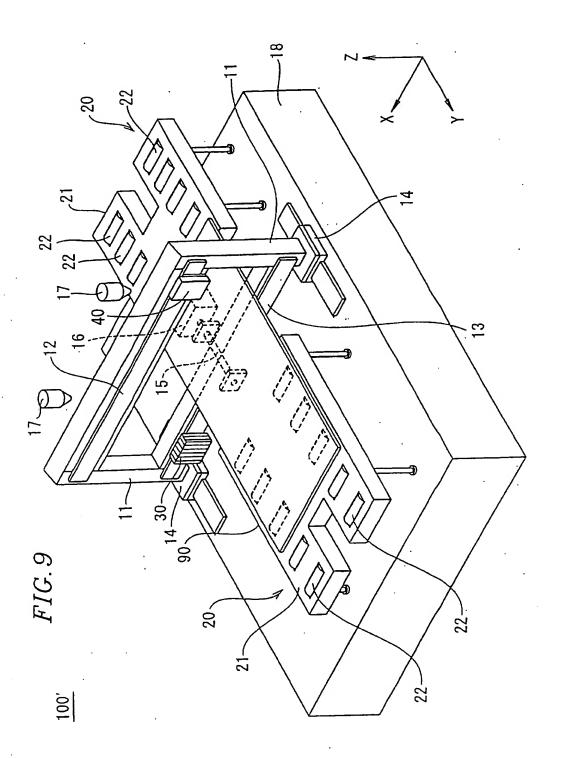
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Substrate Cutting Method
ors: Kenii OTODA et al.

Title: Brittle Substrate Cutting System and
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Inventors: Kenji OTODA, et al.
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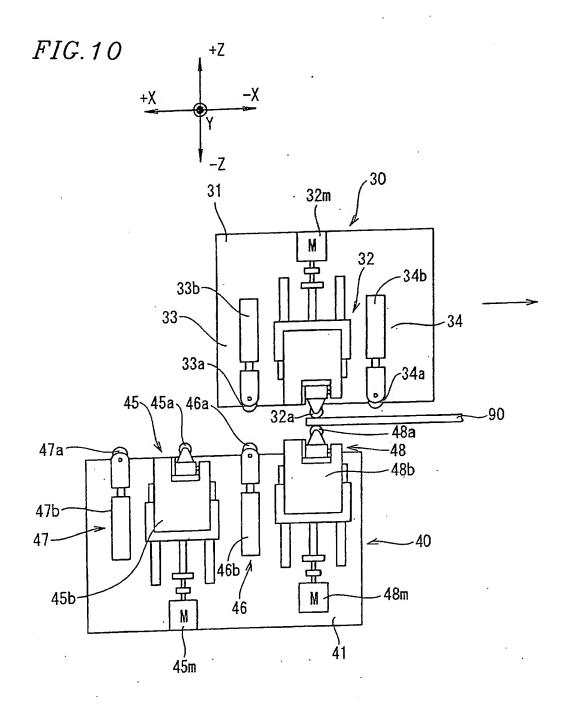


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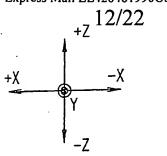
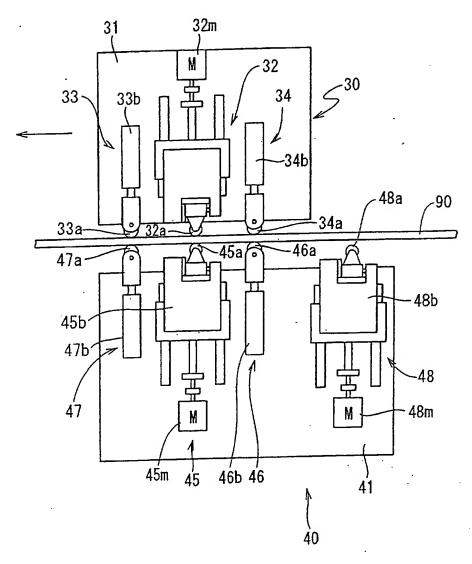
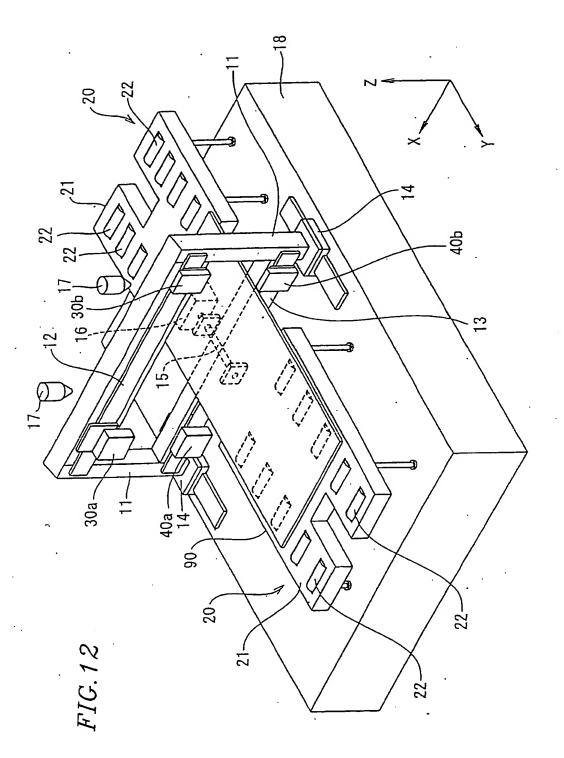


FIG. 11



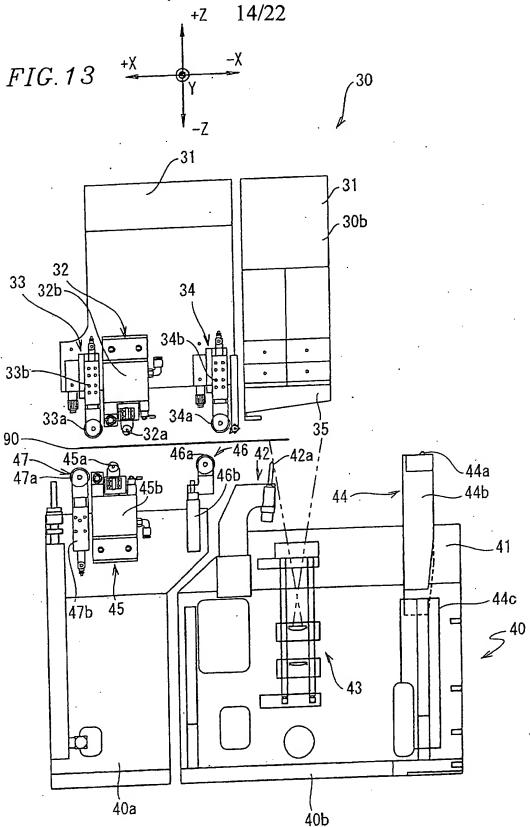
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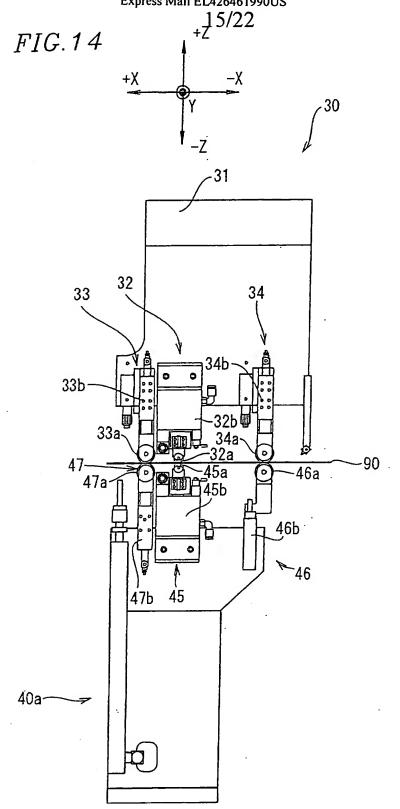
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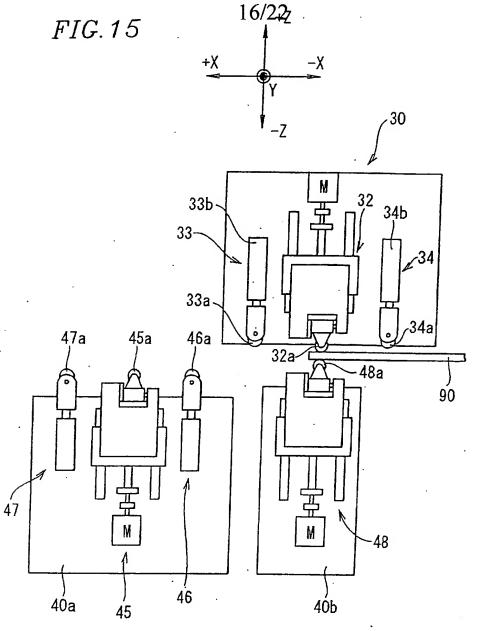
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Docket No. 49288.1600

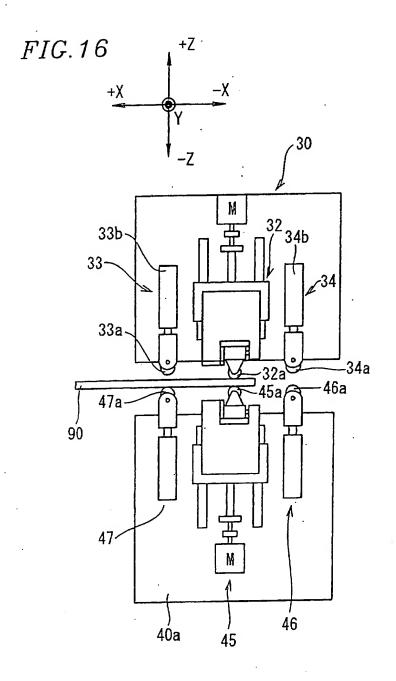
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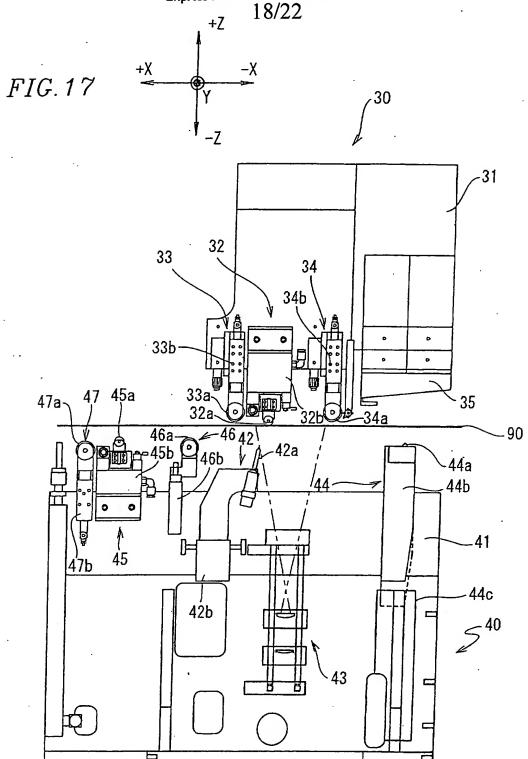
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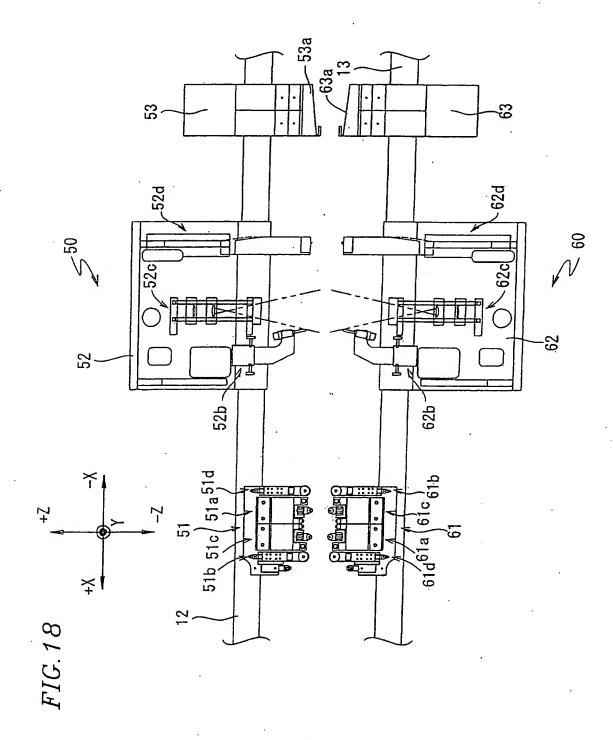


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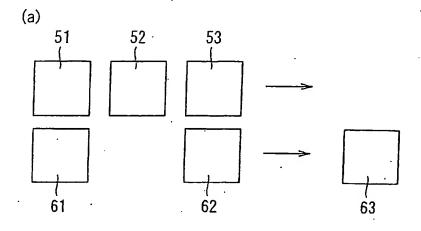


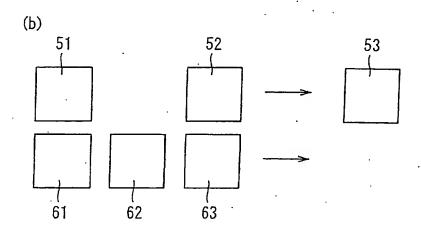
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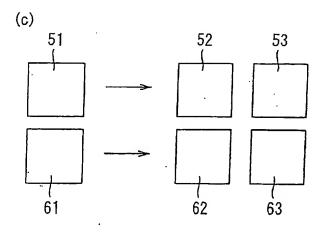


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FIG. 19



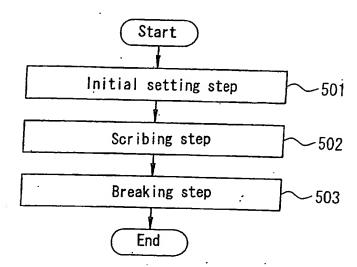




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FIG.20



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